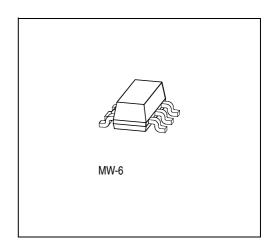


GaAs MMIC CMY 211

Data Sheet

- Linear Mixer with integrated LO-Buffer
- High Input-IP3 of typical 17.5 dBm
- Very low LO-Power demand of typ. 0 dBm
- Suited for Up- and Down-Conversion
- Wide LO-Frequency Range
   500 MHz to > 2.5 GHz
- Wide LO-Level Range
- Single ended Ports
- RF- and IF-Port Impedance 50  $\Omega$
- Operating Voltage Range: < 3 to 6 V</li>
- Very low Current Consumption of typical 2.5 mA
- All Gold Metallization

**ESD**: Electrostatic discharge sensitive device Observe handling Precautions!



Туре	Marking	Ordering Code (tape and reel)	Package <sup>1)</sup>
CMY 211	M4s	Q62702-M0017	MW-6

<sup>1)</sup> For detailed dimensions see Page 7.

# **Maximum Ratings**

Parameter	Port	Symbol	Limit	Values	Unit
			min.	max.	
Supply Voltage	4	$V_{DD}$	0	6	V
DC-Voltage at LO Input	3	$V_3$	-3	0.5	V
DC-Voltage at RF-IF Ports <sup>1)</sup>	1, 6	V <sub>1,6</sub>	- 0.5	+ 0.5	V
Power into RF-IF Ports	1, 6	$P_{IN,RF}$	_	17	dBm
Power into LO Input	3	$P_{IN,LO}$	_	10	dBm
Channel Temperature	_	$T_{Ch}$	_	150	°C
Storage Temperature	_	$T_{stg}$	- 55	150	°C

For DC test purposes only, no DC voltages at pins 1, 6 in application.



## **Thermal Resistance**

Parameter	Symbol	Value	Unit
Channel to Soldering Point (GND)	$R_{thChS}$	≤ 100	K/W

## **Electrical Characteristics**

 $T_{\rm A}$  = 25 °C;  $V_{\rm DD}$  = 3 V, see test circuit;  $f_{\rm RF}$  = 808 MHz;  $f_{\rm LO}$  = 965 MHz;  $P_{\rm LO}$  = 0 dBm;  $f_{\rm IF}$  = 157 MHz, unless otherwise specified

Parameters	Symbol	Li	mit Valu	ies	Unit	Test
		min.	typ.	max.		Conditions
Operating Current	$I_{OP}$	_	2.5	4.0	mA	_
Conversion Loss	$L_{C}$	_	6.0	7.5	dB	_
SSB Noise Figure	$F_{SSB}$	_	6.0	_	dB	_
2 Tone 3 <sup>rd</sup> Order IMD	$d_{IM3}$	_	41	_	dBc	$P_{ m RF1} = - \ 3 \ { m dBm}$ $P_{ m RF2} = - \ 3 \ { m dBm}$ $f_{ m RF1} = 806 \ { m MHz};$ $f_{ m RF2} = 810 \ { m MHz};$ $f_{ m LO} = 965 \ { m MHz}$
3 <sup>rd</sup> Order Input Intercept Point	IP3 <sub>IN</sub>	16	17.5	_	dBm	_
LO Leakage at RF/IF-Port (1, 6)	P <sub>LO 1, 6</sub>	_	<b>– 13</b>	_	dBm	_



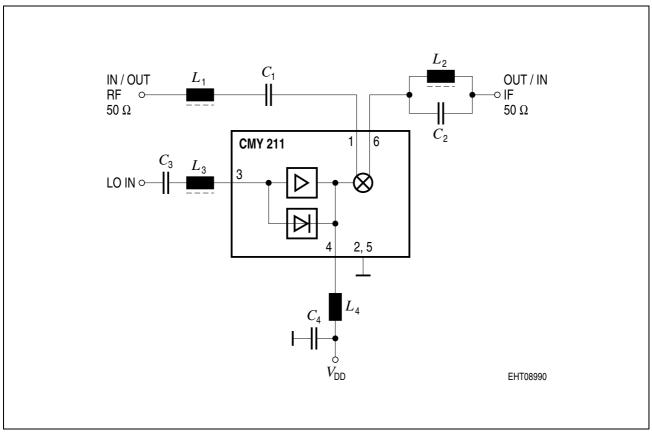


Figure 1 Test Circuit/Application Example

#### **Notes for External Elements**

 $L_1$ ,  $C_1$ : Filter for upper frequency.

 $C_2$ ,  $L_2$ : Filter for lower frequency.

Each filter is a throughpath for the desired frequency (RF or IF) and isolates the other frequency (IF or RF) and its harmonics.

These two filters must be connected to pin 1 and pin 6 directly.

Parasitic capacitances at the ports 1 and 6 must be as small as possible.

 $L_4$  and  $C_4$  are optimized by indicating lowest  $I_{\rm OP}$  at used LO-frequency; same procedure for  $L_3$ .

The ports 1, 3 and 6 must be DC open.

## **Element Values for 800 MHz Test and Application Circuit**

$f_{LO}$	$F_{RF}$	$F_{IF}$	$L_1$	$C_1$	$L_2$	$C_2$	$L_3$	$C_3$	$L_4$	C <sub>4</sub>
MHz	MHz	MHz	nH	pF	nH	pF	nH	pF	nH	pF
965	808	157	8.2	3.9	8.2	3.9	6.8	47	15	33



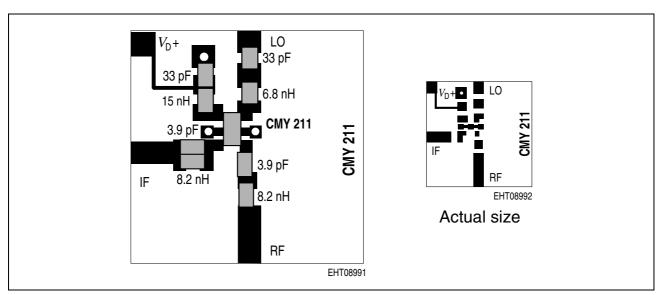


Figure 2 PCB-Layout for 800 MHz Test and Application Circuit

# **Typical Lumped Element Values for Different RF-Frequencies**

$\overline{f_{\sf RF}}$	$L_1$	<i>C</i> <sub>1</sub>	$L_2$	$C_2$
MHz	nH	pF	nH	pF
400	12	15	12	12
450	12	12	12	10
900	8.2	3.9	8.2	3.3
1500	3.3	2.7	3.3	2.2
1800	3.3	2.2	3.3	1.8
2000	3.3	1.8	3.3	1.2
2400	1.8	2.7	1.8	1.5

# **Typical Lumped Element Values for Different LO-Frequencies**

$f_{LO}$	$L_3$	$C_3$	$L_4$	$C_4$
MHz	nH	pF	nH	pF
500	15	82	47	82
750	6.8	33	22	33
800	6.8	33	18	33
950	6.8	27	15	27



### Typical Lumped Element Values for Different LO-Frequencies (cont'd)

$\overline{f_{LO}}$	$L_3$	$C_3$	$L_4$	C <sub>4</sub>
MHz	nH	pF	nH	pF
1100	6.8	27	12	27
1400	6.8	22	6.8	22
1600	6.8	18	4.7	18
1800	6.8	15	3.3	15
2000	6.8	12	2.2	12
2100	6.8	12	1.8	12
2300	4.7	12	1.2	12

#### **General Description and Notes**

The CMY 211 is an all port single ended general purpose Up- and Down-Converter. It combines small conversion losses and excellent intermodulation characteristics with a low demand of LO- and DC-power.

The internal level controlled LO-Buffer enables a good performance over a wide LO level range.

The internal mixers principle with one port RF and IF requires a frequency separation at pin 1 and 6 respectively.

#### Note 1

Best performance with lowest conversion loss is achieved when each circuit or device for the frequency separation meets the following requirements:

**Input Filter**: Throughpass for the signal to be mixed; reflection of the mixed signal

and the harmonics of both.

Output Filter: Throughpass for the mixed signal and reflection of the signal to be

mixed and the harmonics of both.

The impedance for the reflecting frequency range of each filter toward the ports 1 and 6 should be as high as possible.

In the simplest case a series- and a parallel- resonator circuit will meet these requirements but also others as appropriate drop in filters or micro stripline elements can be used.

The two branches with filters should meet immediately at the package leads of the port 1 and 6.

Parasitic capacitances at these ports must be kept as small as possible.

The mixer also can be driven with a source- and a load impedance different to 50  $\Omega$ , but performance will degrade at larger deviations.



### Note 2

The LO-Buffer needs an external inductor  $L_4$  at port 4; the value of inductance depends on the LO frequency. It is tuned for minimum  $I_{OP}$  consumption into port 4.

#### Note 3

The LO Input impedance at Port 3 can be matched with a series inductor. It also can be tuned for a minimum current  $I_{OP}$  into port 4.  $C_3$  is a DC blocking capacitor.

Since the input impedance of port 3 can be slightly negative at lower frequencies, the source reflection coefficient should be kept below 0.8 ( $Z_0 = 50 \Omega$ ) within this frequency range.

The Conversion Noise Figure  $F_{\rm SSB}$  is corresponding with the value of Conversion Loss  $L_{\rm C}$ . The LO signal must be clean of noise and spurious at the frequencies  $f_{\rm LO} \pm f_{\rm IF}$ .

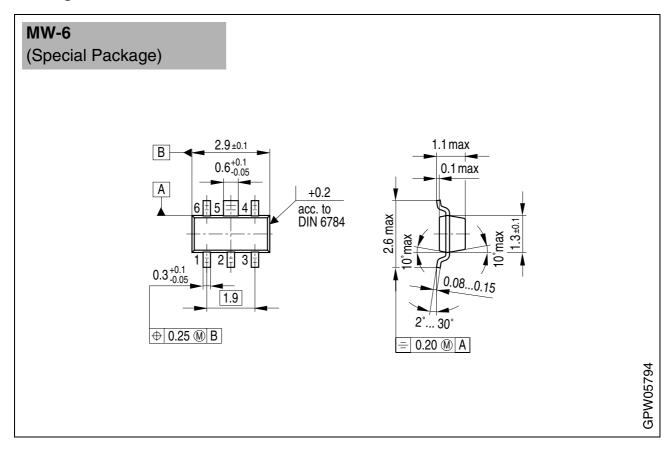
# **Package Parameters**

Dim.	min.	nom.	max.	Gradient	Remark
A	_	_	1.1	_	_
A <sub>1</sub>	_	_	0.1	_	_
$\overline{A_2}$	_	_	1.0	_	_
b	_	0.3	_	_	_
b <sub>1</sub>	_	0.6	_	_	_
С	0.08	_	0.15	_	_
D	2.8	_	3.0	_	_
E	1.2	_	1.4	_	_
lel	_	0.95	_	_	_
le <sub>1</sub> l	_	1.9	_	_	_
H <sub>E</sub>	_	_	2.6	_	_
L <sub>E</sub>	_	_	0.6	_	_
a	_	_	_	max 10°	1)
q	_	_	_	2° 30°	_

<sup>1)</sup> Applicable on all case top sides.



# **Package Outlines**



## **Sorts of Packing**

Package outlines for tubes, trays etc. are contained in our Data Book "Package Information".

SMD = Surface Mounted Device

Dimensions in mm